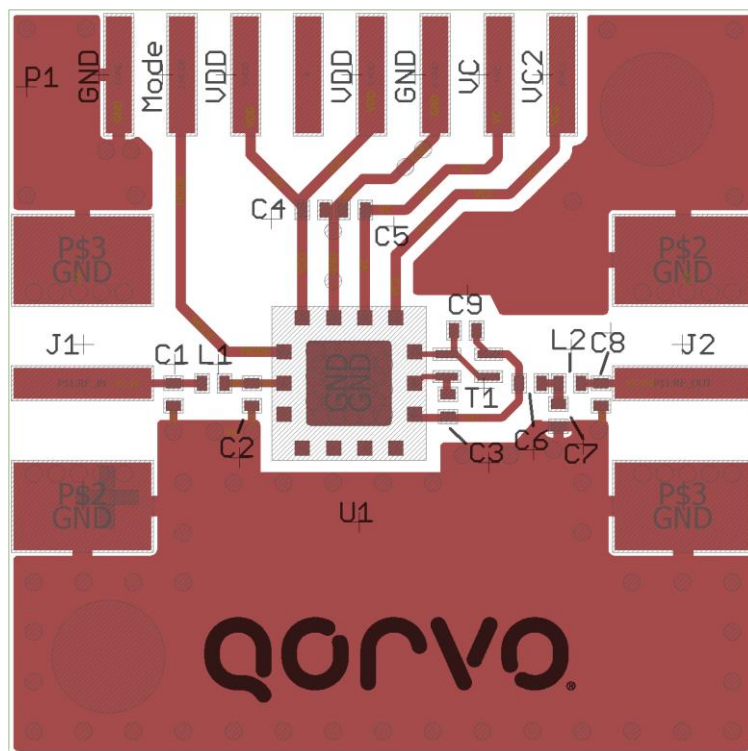
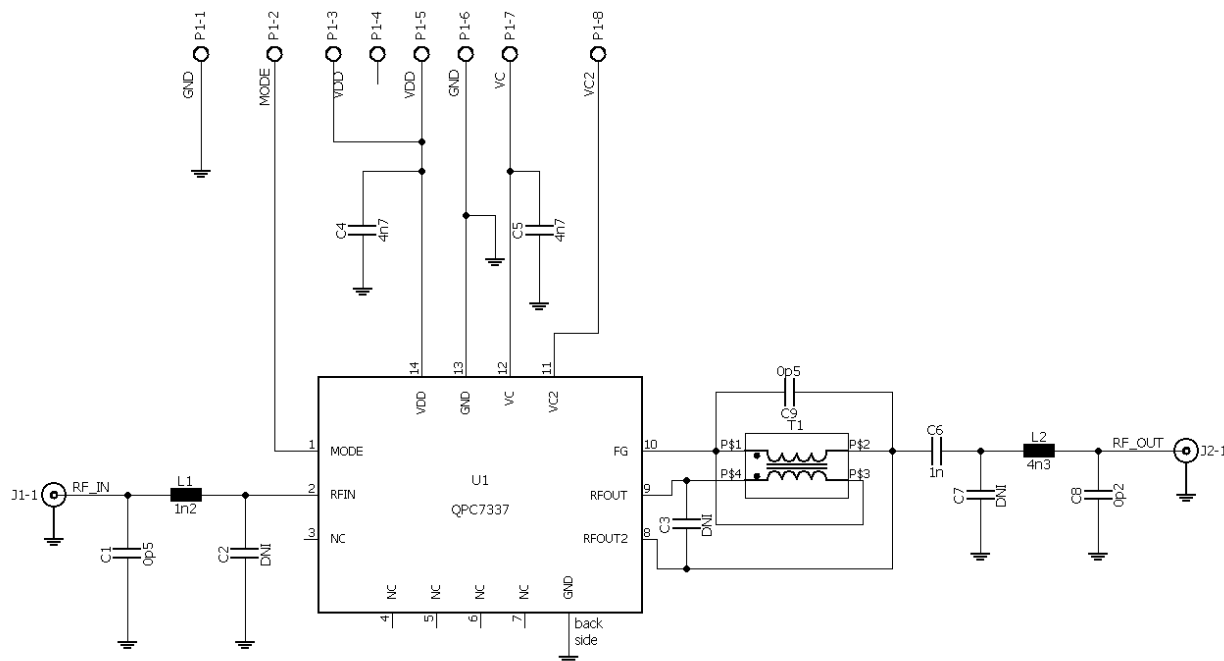


Evaluation Board Assembly Drawing



The ground plane of the QPC7337 module should be soldered onto a board equipped with thermal vias. We recommend a 0.35mm (#80/.0135") diameter bit for drilling via holes and a final plated thru diameter of 0.25mm (0.010"). In any case the module backside temperature should not exceed 110 °C.
Evaluation board PCB: FR4, double sided, 1.5mm, 35um Cu

Evaluation Board Schematic



Evaluation Board Bill of Materials (BOM)

Ref. Designator	Value, package	Description	Manufacturer	Part Number
C1	0.5pF, C0G, 0402	Chip capacitor	MURATA, TAIYO YUDEN	
C2, C3, C7	DNI			
C4, C5	4.7nF, X7R, 0402	Chip capacitor	MURATA, TAIYO YUDEN	
C6	1nF, X7R, 0402	Chip capacitor	MURATA, TAIYO YUDEN	
C9	0.5pF, C0G, 0402	Chip capacitor	MURATA, TAIYO YUDEN	
C8	0.2pF, C0G, 0402	Chip capacitor	MURATA, TAIYO YUDEN	
L1	1.2nH, 0402	Chip inductor	MURATA	LQG15
L2	4.3nH, 0402	Chip inductor	MURATA	LQG15
T1		Transformer	MURATA	DXW21BN7511TL08
J1, J2		Connector F-type, female	Amphenol	222181
P1		Connector, 2.54mm pin spacing, optional	various	
U1		Variable equalizer	QORVO	QPC7337

Notes: C1, L1, C9, L2 and C8 may be modified in target application circuit for S11 and S22 optimization